

ABSTRACT OF THE DISCLOSURE

A semiconductor package includes a package body containing an integrated-circuit chip having an optical sensor. The package can be fitted into an object having two parts suitable for being coupled. A board in the object is provided with electrical connection tracks. The package is placed in a position such that the optical sensor is located facing an opening in the object. The package body carries, on the one hand, resilient rear electrical connection leads that project from a rear face and are electrically connected to the said chip and has, on the other hand, a front bearing surface, such that, when the package body is fitted into the object adjacent the board and when the parts of the object are coupled, the front bearing surface of the body bears on an inner surface of a part of the object and the resilient rear leads bear resiliently on the respective electrical connection tracks of the board.